


# **Intel High-Performance Computing Technologies for Engineering**

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Intel GmbH



**Intel**  
**High-Performance Computing**  
**Technologies for Engineering**

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Intel EMEA

Byte = 8 bits  
Kilobyte =  $10^3$   
Megabyte =  $10^6$   
Gigabyte =  $10^9$   
Terabyte =  $10^{12}$   
Petabyte =  $10^{15}$   
Exabyte =  $10^{18}$   
Zettabyte =  $10^{21}$   
Yottabyte =  $10^{24}$

## Risk Factors

Today's presentation contains forward-looking statements. All statements made that are not historical facts are subject to a number of risks and uncertainties, and actual results may differ materially. Please refer to our most recent Earnings Release and our most recent Form 10-Q or 10-K filing available on our website for more information on the risk factors that could cause actual results to differ.

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## The Three Pillars of Science & Engineering



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## High-Performance Computing

**GFLOPS** [10<sup>9</sup>]



yesterday ...

**TFLOPS** [10<sup>12</sup>]



today ...

**PFLOPS** [10<sup>15</sup>]



tomorrow ...

**From Supercomputers to Supercomputing ...  
A Strategic Investment**



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## CAx Challenges

### Shorten Design and Development Time

- Shorten time-to-market/money
- Better Products in all respect
- Reduce expensive and time consuming mechanical tests
- Reduce material (costs, weight, new)
- Optimize design specific features
- Keep competitive advantage

#### Solution:

- High-Performance Computing (HPC)  
Numerical analysis and simulations on high-performance computer systems
- Increase capability and capacity
  - More flexibility and agility to changes
  - More cost effective
  - Simulate physical difficult tasks
  - Better optimization within the design space



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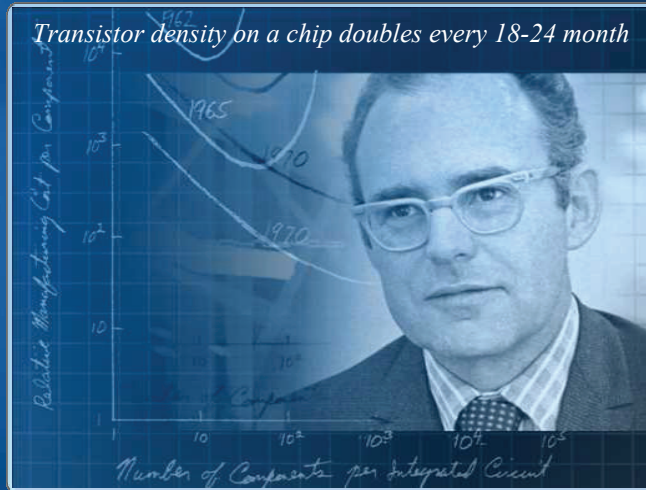
## Changing the way CAD/CAE tools can be used

**From serial to simultaneous workflows,  
reducing the time between an idea and a finished product  
using HPC Technologies**



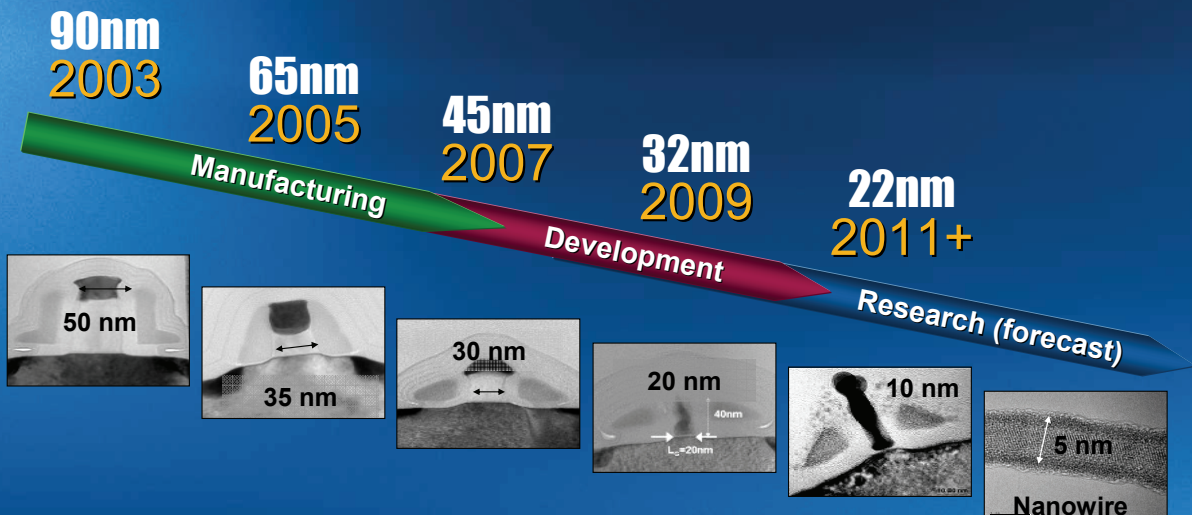
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## Moore's Law is (still) Leading the Chip Industry



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## Ongoing Transistor Miniaturization



Moore's Law is (still) leading the Chip Industry



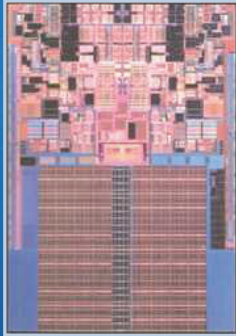
Future options subject to change. Source: Intel

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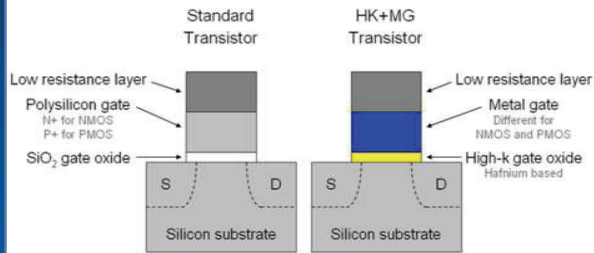
All products, dates, and figures are preliminary and are subject to change without any notice.

## 45nm Volume Manufacturing in 2007

Penryn Die Photo



### High-k + Metal Gate Transistors



High-k + metal gate transistors provide significant performance increase and leakage reduction, ensuring continuation of Moore's Law

Higher Performance with lower Power Consumption



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## Evolving Value Proposition

1960s-1980s

PERFORMANCE

1990s

PRICE/PERFORMANCE

2000s

PRICE/PERFORMANCE/WATT

All Segments: HANDHELDS → CLIENTS → SERVERS → HPC



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## Industry Trend to Multi/Many-Core

*Intel Tera-Scale Computing Research Program:*  
[www.intel.com/go/terascale](http://www.intel.com/go/terascale)

**Energy Efficient Petascale with Multi-threaded Cores**

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## Intel Processors & HPC

<p><b>Large Node, Scalable Shared Memory</b></p> <ul style="list-style-type: none"> <li>• Largest shared memory to 1000s of CPUs and up to 1 PB</li> <li>• Highest level of system RAS for large system stability</li> </ul>	 <b>9000</b> Sequence
<p><b>I/O and Compute Scalability</b></p> <ul style="list-style-type: none"> <li>• Clustered applications requiring large memory footprints</li> <li>• Tigerton brings a new dimension of MP computing to HPC (2H'07)</li> </ul>	 <b>7x00</b> Sequence
<p><b>Optimal for General Purpose Clusters</b></p> <ul style="list-style-type: none"> <li>• Leading 2-way performance and energy efficiency</li> <li>• Best FLOPS/\$, increased density with new Intel Quad-Core Processors</li> <li>• Enhanced DP platform for HPC and WS (2H'07)</li> </ul>	 <b>5x00</b> Sequence
<p><b>Best Bus Bandwidth (UP Cluster)</b></p> <ul style="list-style-type: none"> <li>• Higher bytes/FLOP and bandwidth density</li> <li>• Form factor, performance/\$ for personal &amp; departmental clusters</li> </ul>	 <b>3x00</b> Sequence

**Optimized solutions for any HPC workload**

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## Multi-Threaded Cores

Intel Tera-Scale Computing Research Program: [www.intel.com/go/terascale](http://www.intel.com/go/terascale)

All Large Core

Mixed Large and Small Core

Many Small Cores

All Small Core

### Energy Efficient Petascale with Multi-threaded Cores

Note: the above pictures don't represent any current or future Intel products

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## Multi/Many-Core Chip Research

Shared Cache

Local Cache

Streamlined IA Core

HD HD Video

CY Crypto

DSP DSP

GFX Graphics

HD

CY

DSP

GFX

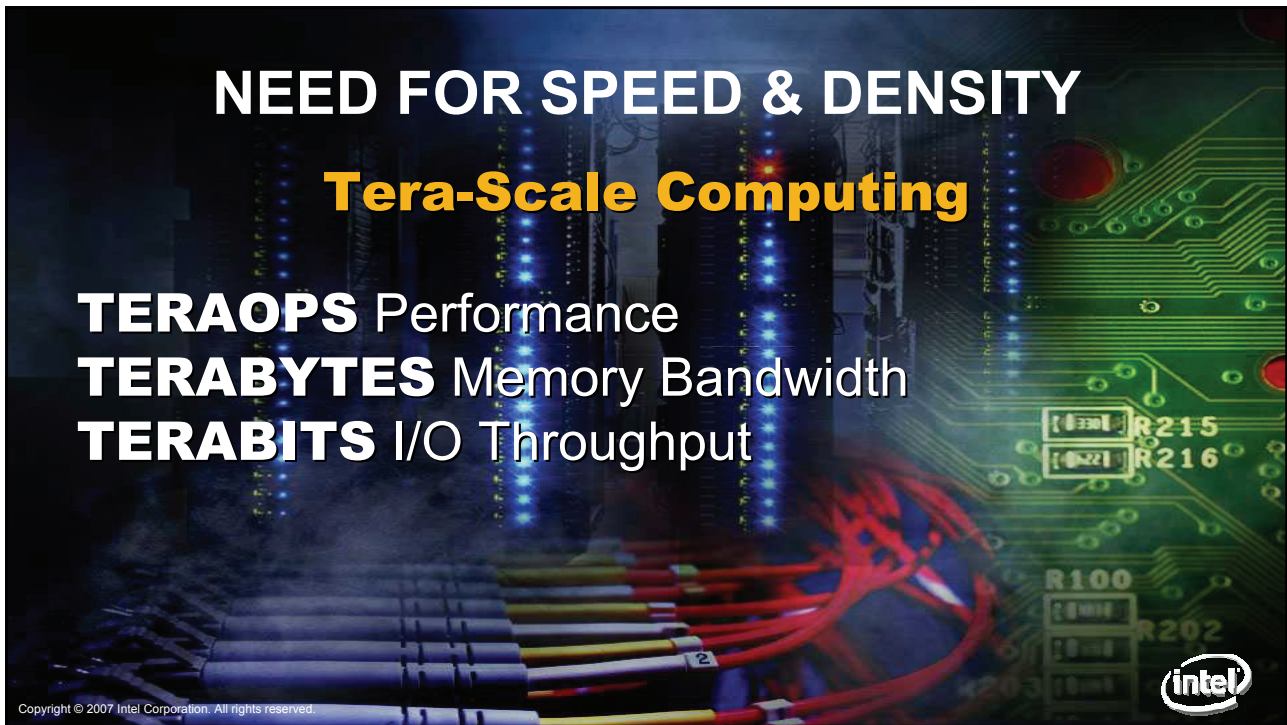
GFX

GFX

Future tera-scale chips could use an array of tens to hundreds of cores with reconfigurable caches, as well as special-purpose hardware accelerators utilizing a scalable on-die interconnect fabric.

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**NEED FOR SPEED & DENSITY**

**Tera-Scale Computing**

**TERAOPS** Performance  
**TERABYTES** Memory Bandwidth  
**TERABITS** I/O Throughput

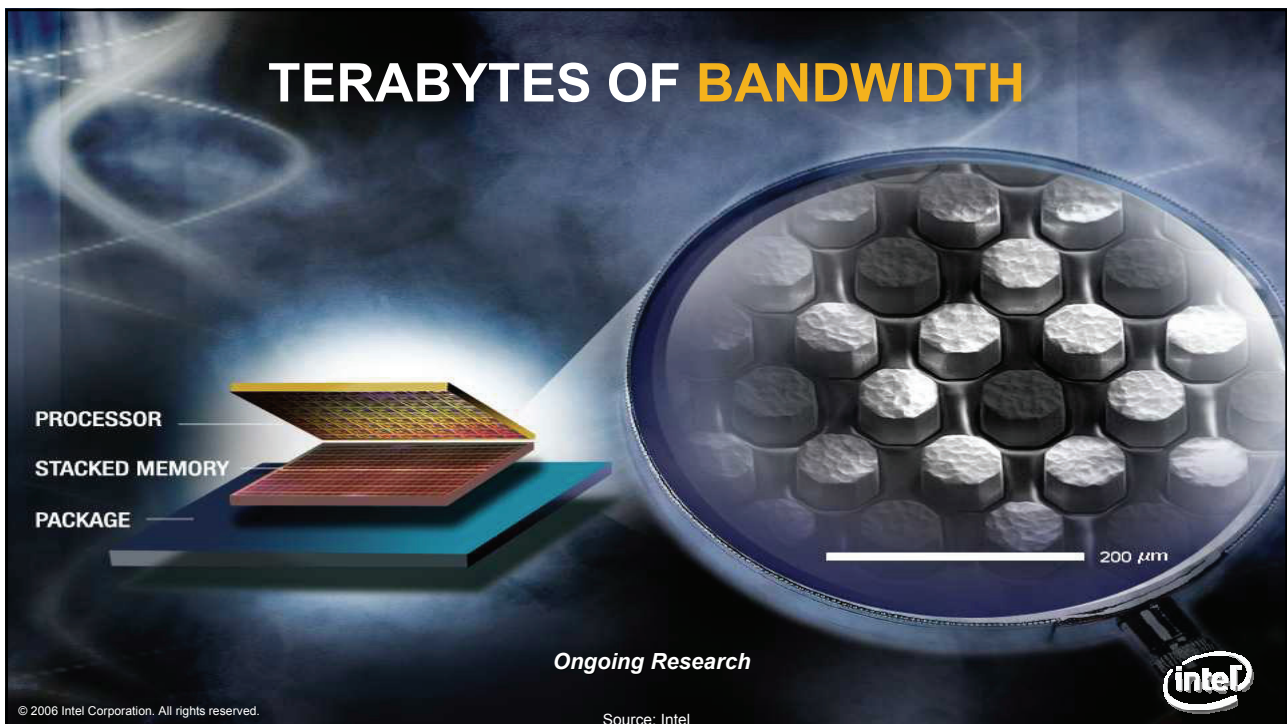
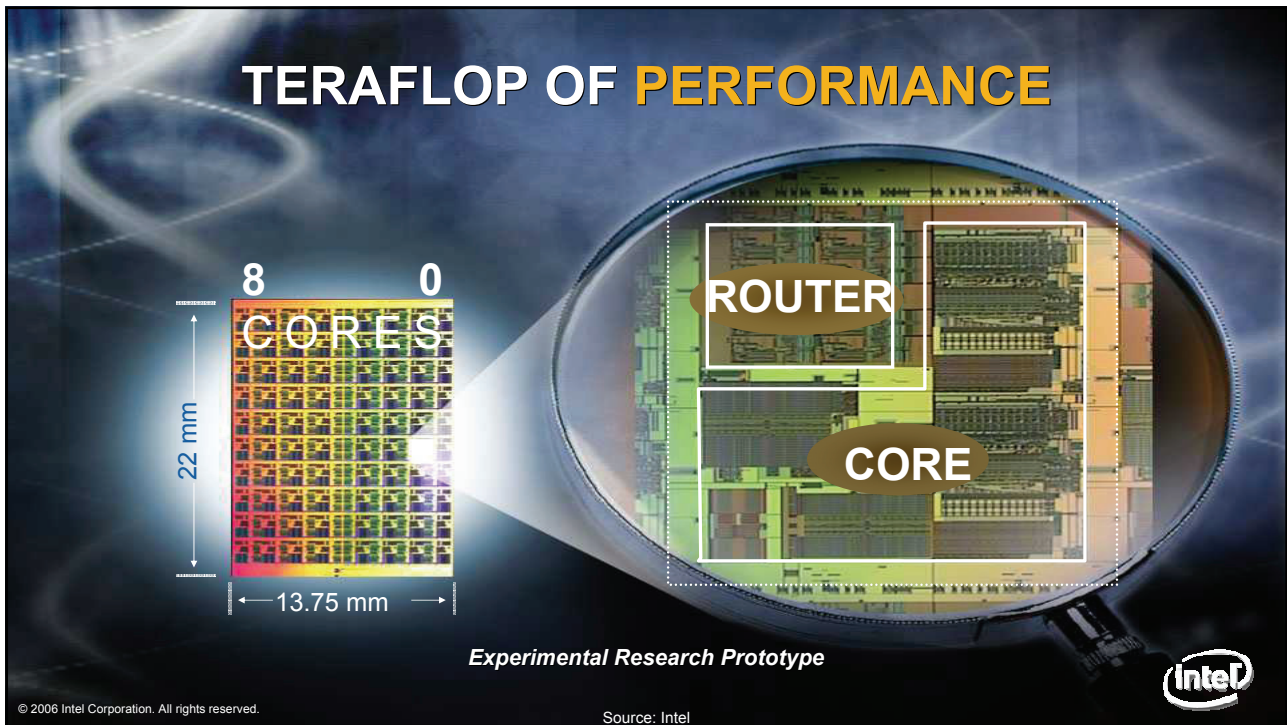
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**1 TFLOPS on a Chip**

**62W**

Experimental Research Test Chip  
100M Transistors – 80 Tiles – 275mm<sup>2</sup>



# TERABITS OF I/O-THROUGHPUT

The diagram illustrates the components of silicon photonics. At the center is a square chip labeled "LOGIC INTEGRATION". Five arrows point towards it from surrounding components: "LASER" (top), "MODULATOR" (top-left), "PHOTO-DETECTOR" (top-right), "LIGHT GUIDES" (bottom-left), and "SELF-ALIGNMENT" (bottom-right). Each component is accompanied by a small image showing its physical structure or a schematic. Below the central chip, the text "BUILDING BLOCKS OF SILICON PHOTONICS" is written. The Intel logo is in the bottom right corner.

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## Industry's First 45nm High-K Products Coming 2H'07/Q1'08 ...

The image displays Intel processor chips. The top row shows two Quad Core chips: Harpertown and Yorkfield. The bottom row shows three Dual Core chips: Wolfdale DP, Wolfdale, and Penryn. Below the chips, the categories "Server", "Desktop", and "Mobile" are listed. The Intel logo is in the bottom right corner.

Intel Forecast


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## Tick/Tock: Our Model for Sustained Microprocessor Leadership



<b>Intel® Core™</b> NEW Microarchitecture 65nm 2006	<b>Penryn</b> Compaction/ Derivative <b>45nm</b> 2007	<b>Nehalem</b> NEW Microarchitecture 45nm 2008	<b>Westmere</b> Compaction/ Derivative <b>32nm</b> 2009	<b>Sandy Bridge</b> NEW Microarchitecture 32nm 2010
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Forecast →

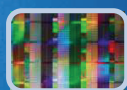


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## Potential HW-Accelerator Options

"Node Fabric"

Multi-Cores




Geneseo/PCIe (Gen 2)




1

3





On-Die







2



Socket



Intel® QuickAssist Technology





Enabling Partnerships



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*“Chip revolution poses problems for programmers:  
Software developers face a culture shock as they  
grapple with the next generation of  
microprocessors”*

NewScientist, 10 March 2007



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## Intel's Software Tools and Support for HPC



### Intel® Cluster Toolkit

**Intel® Thread Checker**  
**Intel® Thread Profiler**  
**Intel® Threading Building Blocks**




Performance | Compatibility | Support | Productivity | Cross-Platform

[www.intel.com/software](http://www.intel.com/software)



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## Levels of Parallelism


### Intel SW Development Tools for HPC

	Serial Core Level	Multi-Core/SMP-Node level	Multi-Node Cluster Level	Grid Level
Programming Model Implementation	C/C++ FORTRAN95	Auto-Parallelization OpenMP* TBB	ClusterOpenMP Intel MPI	Intel GPE (UNICORE)
Correctness & Debugging	IDB	Thread Checker	Message Checker IDB-MPP	
Performance Libraries	MKL IPP	MKL IPP	Cluster MKL	
Performance Analysis	VTune™	VTune Thread Profiler	Trace Analyzer	

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## Intel® Software Tools for Parallelism













- Architectural Analysis**
- Introduce Parallelism**
- Confidence / Correctness**
- Optimize / Tune**

**Architectural Analysis** Visualization of parallel (threaded or MPI) application execution and communication behavior – give valuable insights for application architects and programmers

**Introduce Parallelism** Highly optimized OpenMP\* and MPI library and run-time system for scalable solutions  
MKL threaded and distributed mathematical library


**Confidence / Correctness** Detecting actual and potential Threading and MPI programming and API issues - to address challenges unique to parallel programming

**Optimize / Tune** Valuable insights for performance and scalability tuning of threaded and MPI applications

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## Intel® Cluster Ready

### A Program to make it easier for end users to buy, deploy and use clusters.

- Backed by reference implementations on Intel® Server Platforms (recipes)
  - Including tools to check compliance

### A three-way collaboration between System Vendors/Integrators, Software Vendors, and Intel.

- Systems Vendors' (OEMs) and Integrators' solutions *certified* as compliant with the specification
  - May resell reference recipes or implement their own
- ISVs applications *registered* as compliant with the specification
  - Registered applications will run out-of-the box on any compliant cluster



More than a Cluster Solution Specification



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## Covering the Globe With Software R&D Labs



Over 50 Development Sites Across More Than 20 Countries



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## Conclusions

**End-Users:** The available compute power will continue to increase with flexible system architectures to meet the applications demand and requirements.

**Software Vendors:** Extract the available computational power via parallelization on all levels (multi-core, clusters) utilizing parallel software development tools for new and advanced functionality.

**IT:** Energy and cost efficient solutions continue to evolve providing the needed flexibility and business agility with improved capacity and capabilities.



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